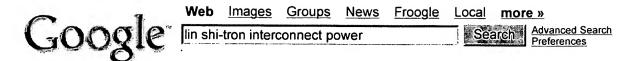
			<del>-</del>		I	
Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	285	(power with ring) same interconnect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/11 12:23
L2	5	(("6795957") or ("6785877") or ("6701509") or ("6978434") or ("20040049754")).PN.	US-PGPUB; USPAT	OR	OFF	2006/04/11 12:23
S65	46569	power with ring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/11 12:22
S66	110	S65 and "716"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 08:34
S67	2	power with (line or grid or stripe) same bus and automatic with place with rout\$3 and slot and ((sparse or upper or higher or dens\$4) with area)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:04
S68	16635	power near3 supply with area	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:04
S69	123	power near3 supply with area same slot	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:05
S70	2652558	power near3 supply with area same slot parallel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:05
S71	119	S69 not S66	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:06
S72	0	automatic with place with rout	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:06

	,					
S73	998	automatic with plac\$5 with rout\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:07
S74	192	automatic with plac\$5 with rout\$3 and power near3 supply	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:07
S75	188	S74 not S66	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:40
S76	9	power near3 supply same sparse near3 area	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:43
S77	45969	interconnect and power near3 bus and power nerar3 line and parallel and metal and layer and slot	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:44
S78	307	S77 and "716"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:45
S79	416	S66 S69 S74 S75	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:45
S80	286	S78 not S79	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:45
S81	269	S80 and (sparse\$3 or dens\$5 or upper or higher)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:03
S82	247	S81 and (plac\$5 and rout\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:20

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S83	18	whitmore\$.xp. and slot	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:01
S84	9	whitmore\$.xp. and sparse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:01
S85	8	S84 not S83	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:02
S86	47207	power with ring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:03
S87	116	S86 and "716"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:03
S88	128	power near3 supply with area same slot	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:03
S89	200 <sup>.</sup>	automatic with plac\$5 with rout\$3 and power near3 supply	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:09
S90	196	S89 not S87	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:03
S91	46823	interconnect and power near3 bus and power nerar3 line and parallel and metal and layer and slot	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:03
S92	318	S91 and "716"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:03

S93	435	S87 S88 S89 S90	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:03
S94	295	S92 not S93	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	·ON	2006/04/05 15:03
S95	278	S94 and (sparse\$3 or dens\$5 or upper or higher)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:03
S96	28727	power same ((upper or higher) with (layer or metal))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:10
S97	186	S96 and "716"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:12
S98	3083	(716/8-14).CCLS.	US-PGPUB; USPAT	OR	OFF	2006/04/05 15:13
S99	100	S96 and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/05 15:13

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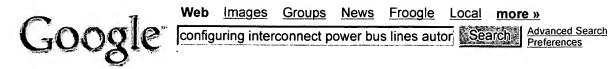
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